

November 11-13, 2022 | Shenzhen, China

CONFERENCE INTRODUCTION

<http://www.apccas2022.org/cfss.html>

The IEEE Asia Pacific Conference on Circuits and Systems (APCCAS) is the regional flagship conference of the IEEE Circuits and Systems Society in Asia. APCCAS 2022 will be held in Shenzhen, China during November 11-13, 2022. Shenzhen is the electronics R&D world center with more than 300 global or regional centers from Fortune Global 500 companies. Besides, Shenzhen is also suitable for tourism, which is ranked No. 2 in the list of best cities for travel by Lonely Planet.

SPECIAL SESSION ON

Session Title | **Energy Efficient Memory Computing Circuit and Architecture**
Special Session Organizer | **Si Xin, Southeast University**

ABSTRACT

Memory computing integrated architecture can break the bottleneck of “memory wall” and “power consumption wall” in the traditional von Neumann architecture, and has developed into an important development direction of high energy efficient chips. Computing-in-Memory (CIM) has been proven to leverage characteristics of different memory technologies to perform energy-efficient computations in different signal domains. This session covers CIM designs implemented using SRAM and NVM technology with improved energy efficiency.

IMPORTANT DATES

Submission of Special Session Full Papers

August 6, 2022

PUBLICATION

Accepted papers will be submitted for inclusion into IEEE Xplore subject to meeting IEEE Xplore's scope and quality requirements. Selected papers will be invited to submit extended full papers to IEEE Transaction on Circuits and Systems I (TCAS-I), IEEE Transaction on Circuits and Systems II (TCAS-II) and IEEE Open Journal of Circuits and Systems (OJCAS).

SUBMISSION METHOD



WORD

Papers for publication must be submitted in full paper electronically. All edition and update must be done up until the submission deadline. Papers submitted to APCCAS Conference will undergo a double-blind review process. Submissions must have all details identifying the author(s) removed from the original manuscript (including authors' names, affiliations, acknowledgments and other related personal information).

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